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	CT1 1 CT2 CT2 CT3 CT4 CT6 CT6 CT6 CT6 CT7 Votage	/F EMI Filter	SD3 SD4 SD5 SD6 SD7 SD7 SAR1	JART Interface JTAG Interface Expansion I/O Interface Waster / Slave Sync Interface			С
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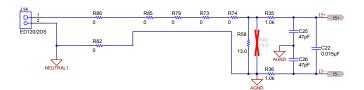
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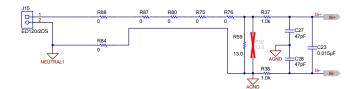
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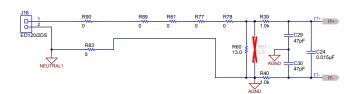
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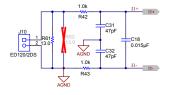


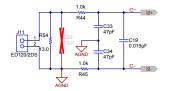


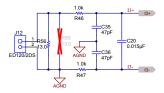




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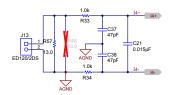




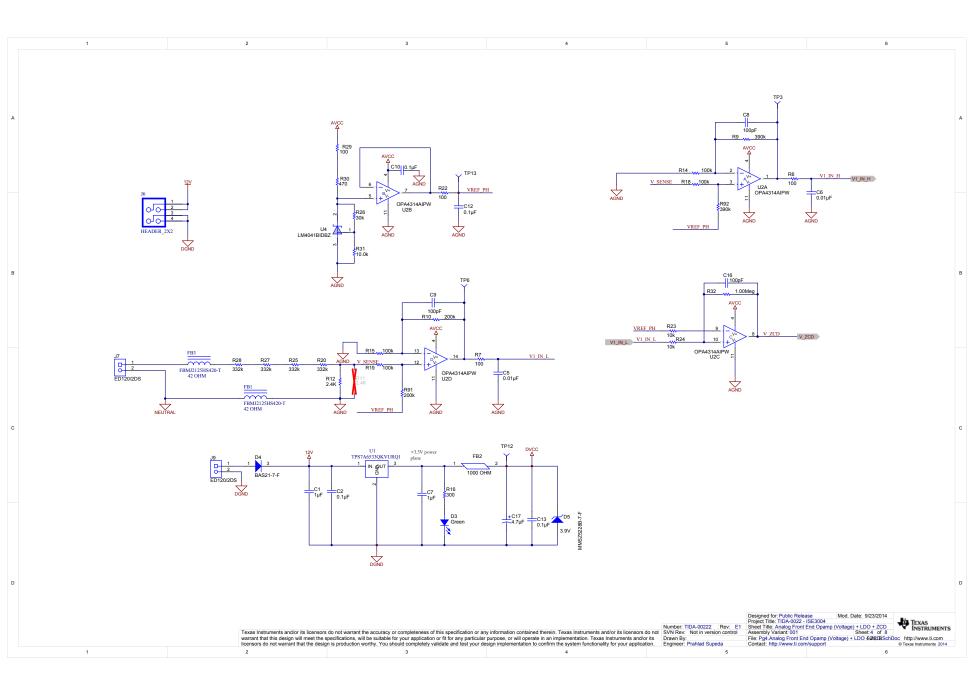


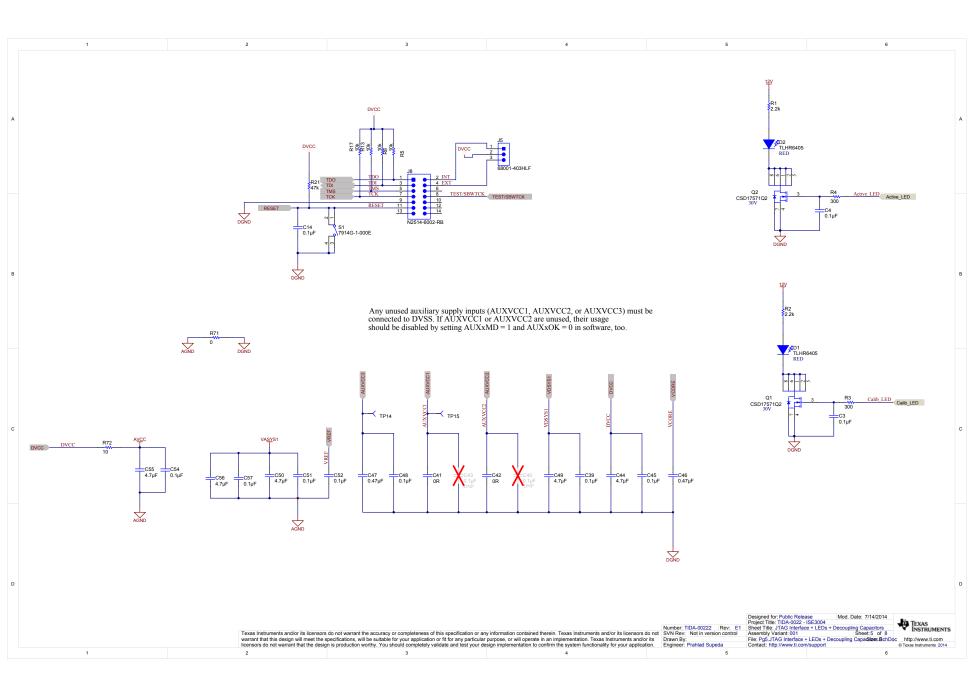
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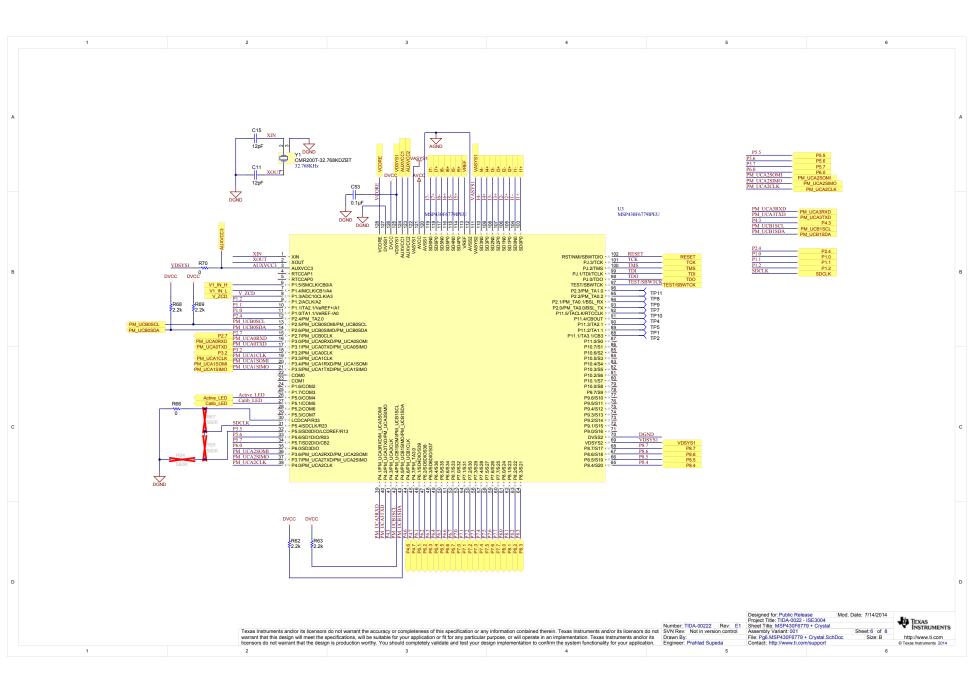
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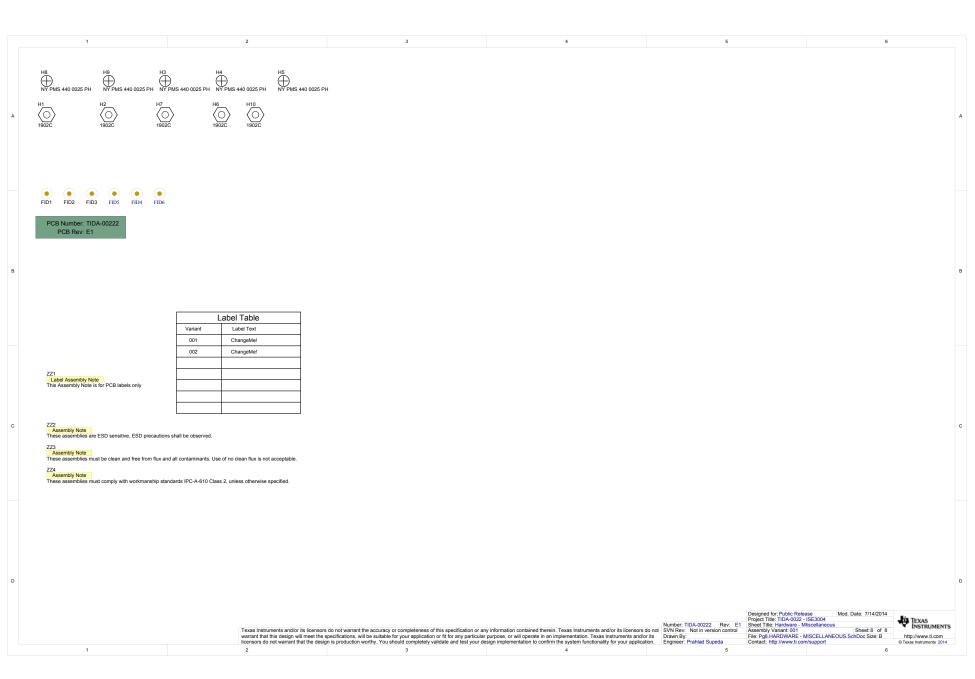




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	SDCLK SDCL P5.6 P5.6 P6.0 P6.0 PM_UCA3200 PM_UC PA_UCA3200 PM_UC PA_UCA3200 PM_UC PA_UCA3200 PM_UC PM_UCA3200 PM_UC PM_UCA3200 PM_UC PM_UCB150A PM_UC P4.7 P4.7	J3 2 P5.5 3 4 P5.7 5 6 PM LICA20KT ARXM07 8 PM LICA20KT AIRXD 9 10 PM LICA20KT BISDA 13 12 PM LICA30KT 15 16 16 67997416HLF 6		1 PM UCAOTXD 2 PM UCAOTXD PM		в
		H 1 P12 P12 O 2 P11 P13 O 4 P14 P13 O 4 P14 P13 O 4 P14 P13 O 6 P14 P14 O 7 P32 PM O 7 P32 PM O 6 PM UCAISM PM UCAISM O 7 P12 PM UCAISM PM UCAISIND PM UCAISM PM UCAISMO PM UCAISIND PM UCAISINO PM UCAISINO HEADER_2XS S S				5
	P6.1 P6.1 P6.3 P6.3 P6.5 P6.5 P6.6 P6.7 P6.1 P7.1 P7.3 P7.5 P7.5 P7.5 P7.5 P8.1 P8.3 P8.3 P8.3 P8.7 P8.7	3 4 P64 P64 5 6 P66 P84 7 8 P70 P65 9 10 P72 P74 11 12 P74 P72 13 14 P76 P75 17 18 P82 P80				с

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